

General Description

The 4003 uses advanced trench technology to provide excellent RDS(ON). The device well suited for high current applications.

Features

- P-Channel MOSFET
- Fast Switching
- Low ON-resistance
- 100% EAS Guaranteed
- RoHS Compliant

Product Summary

BVDSS	RDSON	ID
-40V	20mΩ	-27A

Applications

- DC/DC converters
- Inverter
- Power Supplies

TO-252/251 Pin Configuration**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-40	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_c = 25^\circ C$	Continuous Drain Current ¹	-27	A
$I_D @ T_c = 100^\circ C$	Continuous Drain Current ¹	-21	A
I_{DM}	Pulsed Drain Current ²	-54	A
EAS	Single Pulse Avalanche Energy ³	64	mJ
I_{AS}	Avalanche Current	-27	A
$P_D @ T_c = 25^\circ C$	Total Power Dissipation ⁴	35	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient ¹	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction -Case ¹	---	3.6	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=-250\mu\text{A}$	-40	---	---	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=-10\text{V}$, $I_D=-8\text{A}$	---	14	20	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$, $I_D=-5\text{A}$	---	18	28	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=-250\mu\text{A}$	-1	---	-2.5	V
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=-32\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	-1	uA
		$V_{\text{DS}}=-32\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=55^\circ\text{C}$	---	---	-5	
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{\text{DS}}=-10\text{V}$, $I_D=-10\text{A}$	---	17	---	S
R_g	Gate Resistance	$V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	2	---	Ω
Q_g	Total Gate Charge	$V_{\text{DS}}=-20\text{V}$, $V_{\text{GS}}=-4.5\text{V}$, $I_D=-1\text{A}$	---	12	25	nC
Q_{gs}	Gate-Source Charge		---	3.4	---	
Q_{gd}	Gate-Drain Charge		---	3.3	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=-20\text{V}$, $V_{\text{GS}}=-10\text{V}$, $R_G=3.3\Omega$	---	24	---	ns
T_r	Rise Time		---	15	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	60	---	
T_f	Fall Time		---	8	---	
C_{iss}	Input Capacitance	$V_{\text{DS}}=-15\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	2400	---	pF
C_{oss}	Output Capacitance		---	180	---	
C_{rss}	Reverse Transfer Capacitance		---	105	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,5}	$V_G=V_D=0\text{V}$, Force Current	---	---	-27	A
I_{SM}	Pulsed Source Current ^{2,5}		---	---	-54	A
V_{SD}	Diode Forward Voltage ²	$V_{\text{GS}}=0\text{V}$, $I_s=-1.6\text{A}$, $T_J=25^\circ\text{C}$	---	---	-1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=-20\text{V}$, $V_{\text{GS}}=-10\text{V}$, $L=0.5\text{mH}$, $I_{\text{AS}}=-17\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

This product has been designed and qualified for the consumer market.

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Cmos reserves the right to improve product design ,functions and reliability without notice.